PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT4587439

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKAMITSU MATSUO	07/18/2017
HITOSHI MATSUURA	07/19/2017
YASUYUKI SAITO	07/18/2017
YOSHINORI HOSHINO	07/18/2017

RECEIVING PARTY DATA

Name:	RENESAS ELECTRONICS CORPORATION
Street Address:	2-24, TOYOSU 3-CHOME
City:	KOUTOU-KU, TOKYO
State/Country:	JAPAN
Postal Code:	135-0061

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15700337

CORRESPONDENCE DATA

Fax Number: (703)956-7647

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7039567651

Email: mshapiro@sgriplaw.com, docketing@sgriplaw.com, ctexidor@sgriplaw.com

Correspondent Name: MITCHELL W. SHAPIRO

Address Line 1: 8607 WESTWOOD CENTER DRIVE, SUITE 320

Address Line 4: TYSONS CORNER, VIRGINIA 22182

ATTORNEY DOCKET NUMBER:	XA-13285
NAME OF SUBMITTER:	MITCHELL W. SHAPIRO, REG. NO. 31,568
SIGNATURE:	/Mitchell W. Shapiro/
DATE SIGNED:	09/11/2017

Total Attachments: 6

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FOR APPLICATIONS FILED ON
OR AFTER SEPTEMBER 16, 2012

COMBINED DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN PATENT APPLICATION

DECLARATION

As a below-named inventor, I hereby declare that:

This Declaration is directed to:

☒ the attached application,

OR

☐ United States Application No. or PCT International Application No. ____________________, filed on ______________________________, and was amended on ______________________________,

for the invention entitled Semiconductor Device and Method for Producing the Same .

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any wilful false statement made in this Declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration, receipt and sufficiency of which are hereby acknowledged, paid to me by Renesas Electronics Corporation ("ASSIGNEE"), a corporation or other business entity duly organized under the laws of Japan , whose postal address is 2-24, Toyosu 3-chome, Koutou-ku, Tokyo 135-0061, Japan .

I do hereby sell, assign, and transfer to ASSIGNEE, its successors, legal representatives, and assigns, all my right, title and interest, in the United States of America, in and to the above-entitled invention and the above-identified application, all applications claiming the benefit of the above-identified application, including but not limited to all divisions and continuations, all United States Letters Patent which may be granted for the invention, and any reissues or extensions thereof, to be held and enjoyed by ASSIGNEE, its successors, legal representatives, and assigns, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made;

AND I further covenant and agree that upon request by ASSIGNEE, its successors, legal representatives, and/or assigns, and without further consideration, I will do all lawful acts that

may be necessary or desirable to assist ASSIGNEE, its successors, legal representatives, and/or assigns to obtain and enforce patent protection for the invention in the United States of America, including, but not limited to, communicate with ASSIGNEE, its successors, legal representatives, and/or assigns any facts known to me regarding the invention, testify in any legal proceeding, sign all lawful papers, execute and deliver all papers that may be necessary or desirable to perfect the title to the invention in ASSIGNEE, its successors, legal representatives, and/or assigns, execute all divisional, continuation, and reissue applications, and make all rightful oaths, it being understood that any expense incident to the rendering of such assistance will be borne by ASSIGNEE, its successors, legal representatives, and/or assigns;

And I do hereby authorize and request the Director of the United States Patent and Trademark Office to issue all Letters Patent for the invention to ASSIGNEE, its successors, legal representatives, and assigns in accordance with the terms of this Assignment.

(1) Full name of sole or first inventor: Takamitsu MATSUO
Date: July 18, 2017 Signature: Takamitsu Matsuo
Citizenship: Japanese Residence: Hitachinaka-shi, Ibaraki, Japan
Post Office Address: c/o Renesas Semiconductor Manufacturing Co., Ltd., 751, Horiguchi, Hitachinaka-shi, Ibaraki 312-8504, Japan

(2) Full name of second joint inventor: Hitoshi MATSUURA
Date: Signature:
Citizenship: Japanese Residence: Hitachinaka-shi, Ibaraki, Japan
Post Office Address: c/o Renesas Semiconductor Manufacturing Co., Ltd., 751, Horiguchi, Hitachinaka-shi, Ibaraki 312-8504, Japan

(3) Full name of third joint inventor: Yasuyuki SAITO
Date: Signature:
Citizenship: Japanese Residence: Hitachinaka-shi, Ibaraki, Japan
Post Office Address: c/o Renesas Semiconductor Manufacturing Co., Ltd., 751, Horiguchi, Hitachinaka-shi, Ibaraki 312-8504, Japan

(4) Full name of fourth joint inventor: Yoshinori HOSHINO
Date: July 18, 2017 Signature: Yoshinori Hoshino
Citizenship: Japanese Residence: Hitachinaka-shi, Ibaraki, Japan
Post Office Address: c/o Renesas Semiconductor Manufacturing Co., Ltd., 751, Horiguchi, Hitachinaka-shi, Ibaraki 312-8504, Japan

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(2) Full name of second joint inventor: Hitoshi MATSUURA

Date: July 19, 2017 Signature: Hitoshi Matsuura

Citizenship: Japanese Residence: Hitachinaka-shi, Ibaraki, Japan

Post Office Address: c/o Renesas Semiconductor Manufacturing Co., Ltd., 751, Horiguchi, Hitachinaka-shi, Ibaraki 312-8504, Japan

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Date: ______ Signature: ______

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Date: ______ Signature: ______

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Post Office Address: c/o Renesas Semiconductor Manufacturing Co., Ltd., 751, Horiguchi, Hitachinaka-shi, Ibaraki 312-8504, Japan

SHAPIRO, GABOR and ROSENBERGER PLLC

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(3) Full name of third joint inventor: Yasuyuki SAITO

Date: July 18, 2017 Signature: Yasuyuki Saito

Citizenship: Japanese Residence: Hitachinaka-shi, Ibaraki, Japan

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